

Title (en)  
THIN FILMS OF OXIDIC MATERIALS HAVING A HIGH DIELECTRIC CONSTANT

Title (de)  
DÜNNE FILME OXIDISCHER MATERIALIEN MIT HOHER DIELEKTRIZITÄTSKONSTANTE

Title (fr)  
FILMS MINCES EN MATERIAUX OXYDIQUES A CONSTANCE DIELECTRIQUE ELEVEE

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Application  
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Abstract (en)  
[origin: WO2004028999A2] The invention relates to a method for coating a substrate, according to which a fine-particle suspension of crystalline oxide particles is applied to a substrate, the suspension medium is evaporated, and the coating is sintered on the substrate.

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IPC 8 full level  
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